

What is claimed is:

1. A sputtering device constituted of at least a substrate, a substrate holder for holding said substrate, at least one target for forming a thin film on said substrate, and at least one sputtering cathode in which said target is installed, wherein:
an axis of said target is inclined to an axis of said sputtering cathode, and
said sputtering cathode is rotated on its axis to make said target swing to said substrate.
2. A sputtering device according to claim 1, wherein:
said substrate holder is rotated on its axis.
3. A sputtering device according to claim 2, wherein:
magnets are arranged behind said target and rotated on its axis.
4. A sputtering device according to claim 3, wherein:
said sputtering cathode is inclined to an axis of the substrate.
5. A sputtering device according to claim 4, wherein:
a plurality of sputtering cathodes are arranged to said substrate.
6. A sputtering device according to claim 5, wherein:
said plurality of said sputtering cathodes can be revolved around the axis of the substrate.
7. A sputtering device according to claim 6, wherein:
a shutter is arranged between said sputtering cathodes and said substrate to open and close said sputtering cathodes selectively.

8. A sputtering device according to claim 7, wherein:
a protection shield is provided around said substrate holder to prevent forming a film clung around or beside said substrate holder.
- 5 9. A sputtering device according to claim 8, wherein:
said protection shield can be rotated along a circumferential edge of said substrate holder.
- 10 10. A sputtering device according to claim 1, wherein:
a protection shield is provided around said substrate holder to prevent forming a film clung around or beside said substrate holder.
- 15 11. A sputtering device according to claim 10, wherein:
said protection shield can be rotated along a circumferential edge of said substrate holder.
- 20 12. A sputtering device according to claim 2, wherein:
a protection shield is provided around said substrate holder to prevent forming a film clung around or beside said substrate holder.
- 25 13. A sputtering device according to claim 12, wherein:
said protection shield can be rotated along a circumferential edge of said substrate holder.
- 30 14. A sputtering device according to claim 3, wherein:
a protection shield is provided around said substrate holder to prevent forming a film clung around or beside said substrate holder.
15. A sputtering device according to claim 14, wherein:
said protection shield can be rotated along a circumferential edge

of said substrate holder.

16. A sputtering device according to claim 4, wherein:
a protection shield is provided around said substrate holder to
5 prevent forming a film clung around or beside said substrate holder.

17. A sputtering device according to claim 16, wherein:
said protection shield can be rotated along a circumferential edge
of said substrate holder.

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18. A sputtering device according to claim 5, wherein:
a protection shield is provided around said substrate holder to
prevent forming a film clung around or beside said substrate holder.

15 19. A sputtering device according to claim 18, wherein:
said protection shield can be rotated along a circumferential edge
of said substrate holder.

20. A sputtering device according to claim 6, wherein:
20 a protection shield is provided around said substrate holder to
prevent forming a film clung around or beside said substrate holder.

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21. A sputtering device according to claim 20, wherein:
said protection shield can be rotated along a circumferential edge
25 of said substrate holder.